

Large Current External FET Controller Type Switching Regulators

Single-output High-frequency Step-down Switching Regulator(Controller type)

BD9850FVM



Dual-output Step-up, Negative, Step-down Switching Regulator(Controller type)

BD9851EFV

● Description

The BD9850FVM is a 1-channel DC/DC step-down switching regulator controller, while the BD9851EFV is a 2-channel DC/DC step-down switching regulator controller. The BD9850FVM is adaptable for a maximum switching frequency of 2 MHz and the BD9851EFV for that of 3 MHz. Both provide space saving in all applications.

● Features

- 1) Adaptable for 2-MHz switching frequency (externally variable) (BD9850FVM)
Adaptable for 3-MHz switching frequency (externally variable) (BD9851EFV)
- 2) FET direct drive
- 3) High-accuracy reference voltage (Accuracy: $\pm 1\%$)
- 4) Built-in Under Voltage Lock Out circuit (UVLO)
- 5) Built-in Thermal Shutdown circuit (TSD)
- 6) The BD9851EFV provides two channels:
Channel 1 available for selection of step-down/step-up switching
Channel 2 available for selection of step-down/inverting switching.
- 7) Compact MSOP8 package (BD9850FVM) / HTSSOP-B20 package (BD9851EFV)

● Applications

TFT panel, TA/ Router, digital consumer electronics, PC, and portable CD/ DVD/ DVC

● Product lineup

| | BD9850FVM | BD9851EFV |
|-----------------------------|---|---|
| Input range | 4V to 9V | 4V to 18V |
| Oscillation frequency range | 100kHz to 2MHz | 10kHz to 3MHz |
| External synchronization | Not provided | Not provided |
| Standby function | Not provided | Provided |
| Operating temperature | -40°C to 85°C | -40°C to 85°C |
| Package | MSOP8 | HTSSOP-B20 |

● Absolute maximum ratings (Ta=25°C)

○ BD9850FVM

| Item | Symbol | Rating | Unit |
|------------------------------|--------|-------------|------|
| Power supply voltage | Vcc | 10 | V |
| Storage temperature | Tstg | -55 to +150 | °C |
| Operating temperature | Topr | -40 to +85 | °C |
| Power dissipation | Pd | 587 | mW |
| Maximum junction temperature | Tjmax | +150 | °C |

Reduce by 4.7 mW/°C over 25°C (When mounted on PCB of 70mm×70mm×1.6mm)

○ BD9851EFV

| Item | Symbol | Rating | Unit |
|--|--------|---------------------|------|
| Power supply voltage (Between Vcc and GND) | Vcc | 20 | V |
| Between VREF and GND | VREF | 7 | V |
| Between OUT1 and PVcc1 Between OUT2 and PVcc2 | Vouth | 20 | V |
| Between OUT1, OUT2 and PGND | Voutl | 20 | V |
| Power dissipation | Pd | 1000 ⁽¹⁾ | mW |
| Operating temperature | Topr | -40 to +85 | °C |
| Maximum junction temperature | Tjmax | +150 | °C |
| Storage temperature | Tstg | -55 to +150 | °C |

(1) Reduce by 8.0 mW/°C over 25°C (When mounted on PCB of 70mm×70mm×1.6mm)

● Recommended operating range

○ BD9850FVM

| Item | Symbol | Limits | | | Unit |
|-----------------------|--------|--------|------|------|------|
| | | min. | Typ. | max. | |
| Power supply voltage | Vcc | 4 | 7 | 9 | V |
| Oscillation frequency | fosc | 100 | — | 2000 | kHz |
| Operating temperature | Topr | -40 | — | +85 | °C |

○ BD9851EFV

| Item | Symbol | Limits | | | Unit |
|-----------------------|-----------------|--------|------|-------|------|
| | | min. | Typ. | max. | |
| Power supply voltage | Vcc | 4 | 12 | 18 | V |
| Oscillation frequency | fosc | 10 | 300 | 3000 | kHz |
| Timing resistor | R _{RT} | 3.3 | — | 47 | kΩ |
| Timing capacitor | C _{CT} | 33 | — | 10000 | pF |

Electrical characteristics (Unless otherwise specified, Ta=25°C, Vcc=7V, fosc=600kHz)

| Item | Symbol | Limits | | | Unit | Conditions |
|-------------------------------|---------|--------|-------|-------|------|---------------------|
| | | min. | Typ. | max. | | |
| [Oscillator block] | | | | | | |
| Oscillation frequency | fosc | 510 | 600 | 690 | kHz | RRT = 24kΩ |
| Frequency regulation | FDV | -5 | 0 | 5 | % | Vcc = 4V to 9V |
| Oscillator amplitude voltage | Vpptr | - | 0.5 | - | V | |
| [Soft start/SW block] | | | | | | |
| CTL/SS pin sink current | ISS | -1.90 | -1.00 | 1.00 | μA | VCTL/SS = 1.5V |
| CTL/SS pin clamp voltage | VSS | 2.2 | 2.4 | 2.6 | V | |
| CTL threshold voltage | VCTLTH | 1.2 | 1.3 | 1.4 | V | |
| [PWM comparator block] | | | | | | |
| 0% threshold voltage | D0 | 1.5 | 1.6 | 1.7 | V | fosc = 600kHz |
| 100% threshold voltage | D100 | 2.0 | 2.1 | 2.2 | V | fosc = 600kHz |
| [Error Amp block] | | | | | | |
| Threshold voltage | VIN | 0.98 | 1.00 | 1.02 | V | AV = 0dB |
| Frequency bandwidth | BW | 1.5 | 3.0 | - | MHz | |
| Voltage gain | Av | - | 70 | - | dB | |
| Input bias current | IIB | -150 | -70 | - | A | |
| Maximum output voltage | VCH | 2.3 | 2.4 | 2.6 | V | |
| Minimum output voltage | VCL | - | 0.03 | 0.20 | V | |
| Output source current | IOI | -3.1 | -1.6 | -1.0 | mA | VFB = 1.0V |
| Output sink current | IOO | 12 | 50 | 125 | mA | VFB = 1.0V |
| [VREF block] | | | | | | |
| VREF output voltage | VREF | 2.475 | 2.500 | 2.525 | V | IVREF = 0mA |
| VREF load regulation | ΔVREFIO | - | - | 10 | mV | IVREF = 0mA to -1mA |
| VREF current capacitance | IVREF | -45 | -16 | -1 | mA | |
| [Total device] | | | | | | |
| Standby current | ICCS | 420 | 610 | 960 | μA | |
| Average supply current | ICCA | 3.4 | 5.0 | 7.8 | mA | At no load |
| [Output block] | | | | | | |
| ON resistance | RON | 0.9 | 2.5 | 8.0 | Ω | |
| Output transient time | Tr/Tf | - | 20 | - | nsec | Cout = 1000pF |
| [Under voltage lockout block] | | | | | | |
| Threshold voltage | VUT | 3.7 | 3.8 | 3.9 | V | Vcc sweep down |
| Hysteresis width | VUTHy | 0.05 | 0.10 | 0.15 | V | |

Design guarantee

Not designed to be radiation-resistant.

Electrical characteristics (Unless otherwise specified, Ta=25°C, Vcc=12V, fosc=300kHz, STB=3V)

| Item | Symbol | Limits | | | Unit | Conditions |
|--|---------|----------|-------|-------|------|------------------------|
| | | min. | Typ. | max. | | |
| [Total device] | | | | | | |
| Standby mode circuit current | Iccst | – | – | 5 | μA | STB=0V |
| Operation mode circuit current | Icc | 1.5 | 2.5 | 4.1 | mA | FB1, FB2=0V |
| [Reference voltage block] | | | | | | |
| Output voltage | VREF | 2.475 | 2.500 | 2.525 | V | Io=–0.1mA |
| Input stability | DVli | – | – | 10 | mV | Vcc=4Vto18V, Io=–0.1mA |
| Load stability | DVlo | – | – | 10 | mV | Io=–0.1mA to –1mA |
| Short circuit mode output current | los | –45 | –12 | –3 | mA | |
| [Oscillator block] | | | | | | |
| Oscillation frequency | fosc | 270 | 300 | 330 | kHz | RRT=24kΩ, CCT=220pF |
| Oscillation frequency regulation | Dfosc | –2 | 0 | 2 | % | Vcc=4Vto18V |
| [Error Amp block] | | | | | | |
| Threshold voltage | Vthea | 0.98 | 1.00 | 1.02 | V | Ch1 |
| Input offset voltage | Vofst | –10 | 0 | 10 | mV | Ch2 |
| Common-mode input voltage range | Vcm | 0.3 | – | 2.0 | V | Ch2 |
| Input bias current | Ibias | –150 | –70 | – | nA | |
| Voltage gain | Av | 60 | 75 | 90 | dB | DC Design guarantee |
| Frequency bandwidth | Bw | 3 | 6 | 13 | MHz | MHz Design guarantee |
| Maximum output voltage | Vfbh | VREF–0.1 | – | VREF | V | |
| Minimum output voltage | Vfbl | – | – | 0.1 | V | |
| Output sink current | Isink | 1.6 | 6 | 16 | mA | FB pin |
| Output source current | Isource | –260 | –160 | –90 | μA | FB pin |
| [PWM comparator block] | | | | | | |
| 0% threshold voltage | Vth0 | 1.21 | 1.31 | 1.41 | V | FB voltage |
| 100% threshold voltage | Vth100 | 1.74 | 1.84 | 1.94 | V | FB voltage |
| DTC bias current | Idtc | –1 | – | 1 | μA | |
| [FET driver block] | | | | | | |
| ON resistance | RonN | 1.5 | 3 | 3 | Ω | When OUT=Lo |
| | RonP | 1 | 2 | 2 | Ω | When OUT=Hi |
| SEL1 input voltage range | Vselh | Vcc–0.2 | – | – | V | In step-down switching |
| | Vsell | 0 | – | – | V | In step-down switching |
| [Control block] | | | | | | |
| Threshold voltage | Vstb | 0.6 | 1.5 | 1.5 | V | |
| Sink current | Istb | 6 | 15 | 15 | μA | STB=3V |
| [Short circuit protection circuit (SCP) block] | | | | | | |
| Timer start voltage | Vtime | 2.2 | 2.3 | 2.3 | V | FB voltage |
| Threshold voltage | Vthscp | 1.4 | 1.5 | 1.5 | V | SCP voltage |
| Standby mode voltage | Vstscp | – | 10 | 10 | mV | SCP voltage |
| Source current | Vsosc | –3.2 | –2.0 | –2.0 | μA | SCP=0.75V |
| [Under voltage lockout block (UVLO)] | | | | | | |
| Threshold voltage | Vuvlo | 3.58 | 3.7 | 3.7 | V | Vcc sweep down |
| Hysteresis width | DVuvlo | 0.05 | 0.11 | 0.11 | V | |

Design guarantee

● Characteristic data

(BD9850FVM)

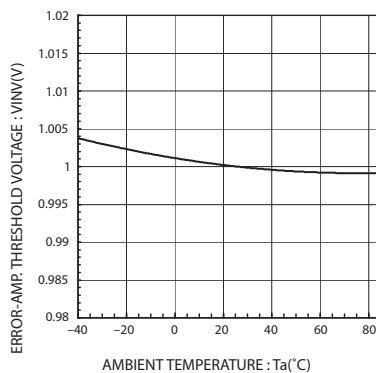


Fig.1 Error Amp threshold voltage vs. Ambient temperature

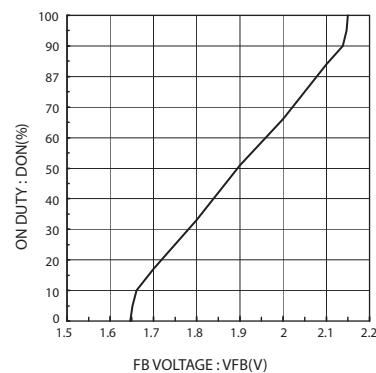


Fig.2 FB voltage vs. ON Duty

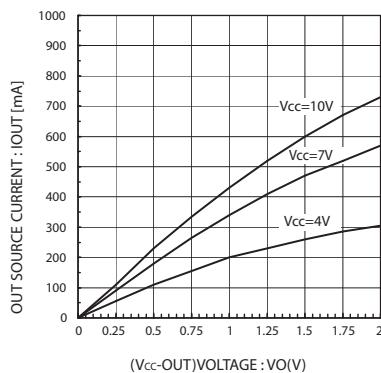


Fig.3 (V_{CC}-OUT) Voltage vs. Output source current

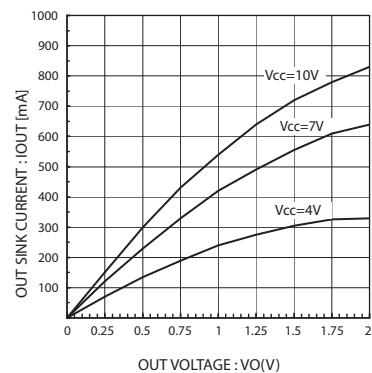


Fig.4 Output voltage vs. Output sink current

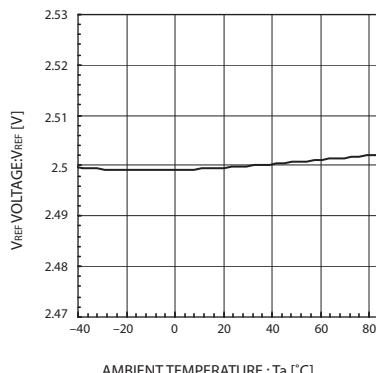


Fig.5 V_{REF} vs. Ambient temperature

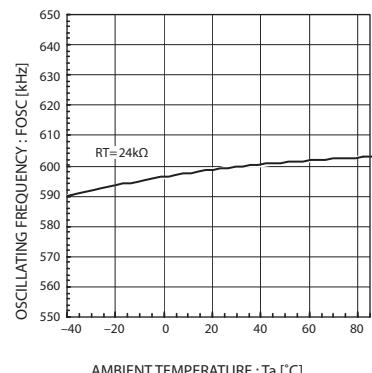


Fig.6 Oscillation frequency vs. Ambient temperature

(BD9851EFV)

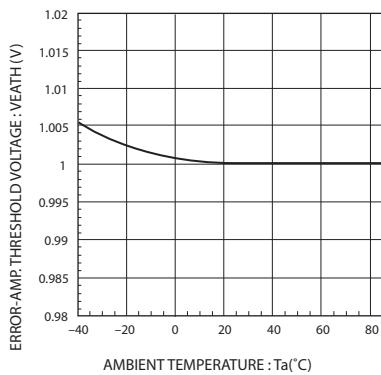


Fig.7 Error Amp threshold voltage vs. Ambient temperature

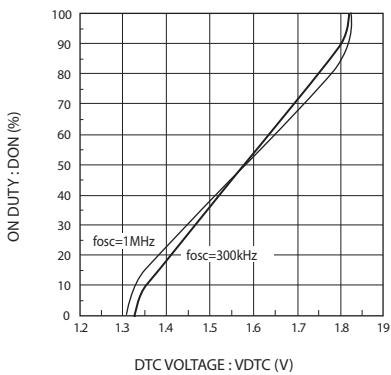


Fig.8 FB voltage vs. ON Duty

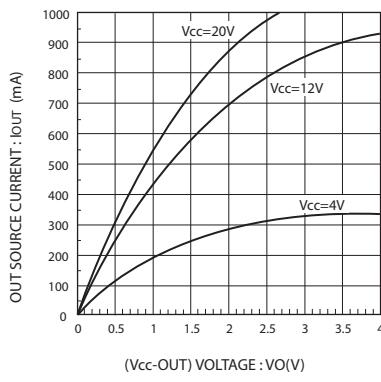


Fig.9 (Vcc-OUT) Voltage vs. Output source current

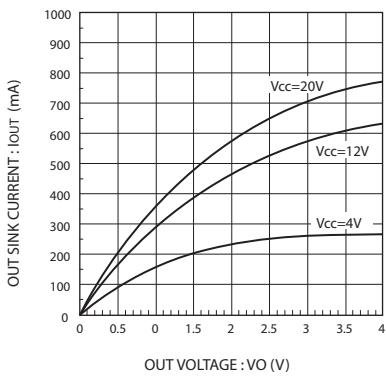


Fig.10 Output voltage vs. Output sink current

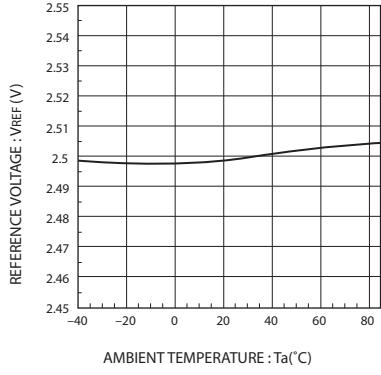


Fig.11 V_{REF} vs. Ambient temperature

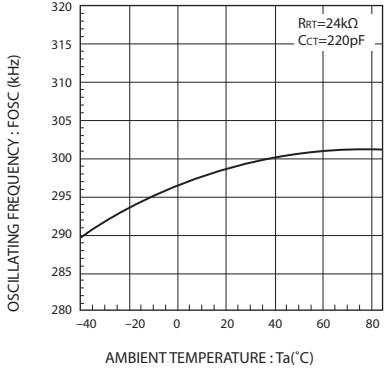


Fig.12 Oscillation frequency vs. Ambient temperature

● Block diagram / Pin assignment

(BD9850FVM)

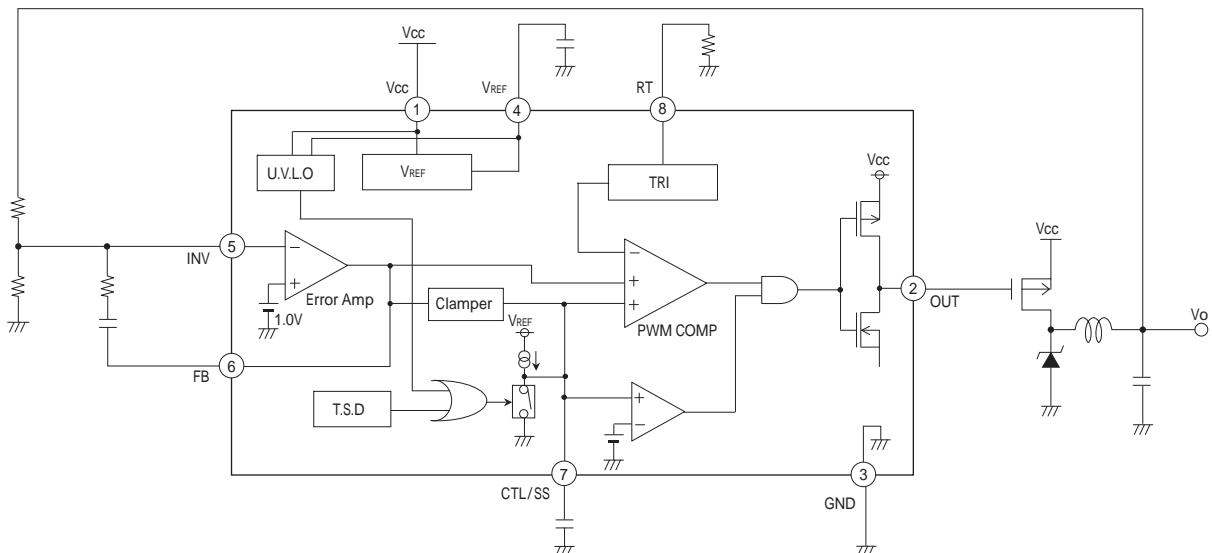


Fig.13 BD9850FVM Block diagram

| Pin No. | Pin name | Function |
|---------|------------------|---|
| 1 | Vcc | Power supply |
| 2 | OUT | FET driver drive output |
| 3 | GND | Ground |
| 4 | V _{REF} | Reference voltage (2.5V±1%) output |
| 5 | INV | Error Amp inverting input |
| 6 | FB | Error Amp output |
| 7 | CTL/SS | Control/Soft start common |
| 8 | RT | Oscillation frequency setting resistor connection |

(BD9851EFV)

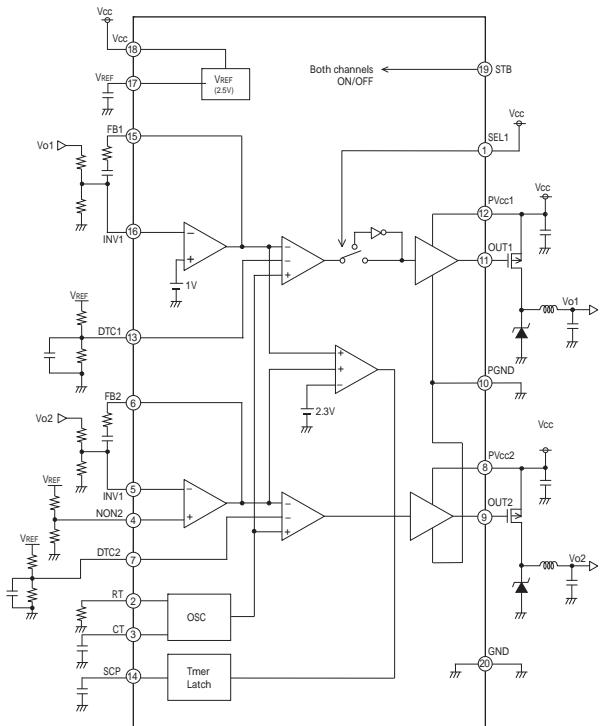
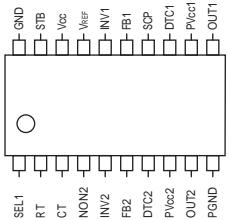


Fig.14 BD9851EFV Block diagram

| Pin No. | Pin name | Function |
|---------|----------------|--|
| 1 | SEL1 | CH1 drive FET setting (Vcc short: P-ch drive, GND short: N-ch drive) |
| 2 | RT | Oscillation frequency setting resistor connection |
| 3 | CT | Oscillation frequency setting capacitor connection |
| 4 | NON2 | Error Amp non-inverting input (CH2) |
| 5 | INV2 | Error Amp inverting input (CH2) |
| 6 | FB2 | Error Amp output (CH2) |
| 7 | DTC2 | Maximum duty/soft start setting (CH2) |
| 8 | PVcc2 | FET driver block power supply input (CH2) |
| 9 | OUT2 | FET driver block output (CH2) |
| 10 | PGND | FET driver block ground |
| 11 | OUT1 | FET driver block output (CH1) |
| 12 | PVcc1 | FET driver block power supply input (CH1) |
| 13 | DTC1 | Maximum duty/soft start setting (CH1) |
| 14 | SCP | Short circuit protection timer setting capacitor connection |
| 15 | FB1 | Error Amp output (CH1) |
| 16 | INV1 | Error Amp inverting input (CH1) |
| 17 | VREF | Reference voltage (2.5V±1%) output |
| 18 | Vcc | Power supply input |
| 19 | STB | ON/OFF control |
| 20 | GND | Ground |
| – | FIN on reverse | Make FIN on the reverse open or ground to GND (pin 20) (However, open FIN on the reverse will degrade radiation performance.) |



● Description of operations

1) Reference voltage block

The reference voltage block generates a constant voltage with temperature compensated through inputting the power supplied from the Vcc pin. The output voltage is 2.5 V, with a $\pm 1\%$ accuracy. To cancel noises, insert a capacitor with a low ESR (several tens of $\mu\Omega$) between the VREF and GND pins. It is recommended to use a ceramic capacitor of $1\mu\text{F}$ for this purpose.

2) Triangular wave oscillator block

By connecting the resistor and capacitor of frequency settings to the RT and CT pins (only to RT pin on the BD9850FVM), a triangular wave will be generated and then input to the PWM comparators of Channels 1 and 2.

3) Error Amp block

The Error Amp block detects the output voltage of the INV pin, amplifies an error with the set output voltage, and then outputs the error from the FB pin. The comparison voltage is 1 V, with a $\pm 2\%$ accuracy. (The Channel 2 of the BD9851EFV uses the NON pin input voltage as a reference.)

Inserting a resistor and capacitor between the INV and FB pins will conduct phase compensation.

4) PWM comparator block

The PWM comparator block converts the output voltage (FB voltage) into a PWM waveform and outputs it to the FET driver.

<Dead time control> (Only available on the BD9851EFV)

Inputting a voltage, divided by resistance of the VREF pin in the DTC pin, will allow maximum ON duty setting.

<Soft start (BD9850FVM)>

Inserting a capacitor between the CTL/SS and GND pins will allow the soft start function to control the rising output voltage.

<Soft start (BD9851EFV)>

Inserting a capacitor between the DTC and GND pins will allow the soft start function to control the rising output voltage.

Furthermore, the overshoot of output voltage at startup can be derated. Adding a Schottky diode between the FB and DTC pins will make it possible to suppress the overshoot rate (only available with step-down application).

5) FET driver block

This block is a push-pull type driver enabling direct drive of external MOS FET.

<Setting of step-down/step-up switching (Only available for Channel 1 of BD9851EFV)>

For the Channel 1, SEL1 pin setting will determine the application function.

Set the SEL1 pin to step-down (P-ch drive) mode for short-circuiting Vcc or to step-up (N-ch drive) mode for short-circuiting GND.

Furthermore, be sure to short-circuit the SEL1 pin to Vcc or GND pin.

6) Standby function

(BD9850FVM)

The CTL/SS pin allows for output ON/OFF control. Set the CTL/SS pin voltage to "H" to activate the output ON control.

(BD9851EFV)

The STB pin allows for output ON/OFF control. Set the STB pin voltage to "H" to activate the output ON control.

The standby mode circuit current should be set to less than 5 μA .

7) Short circuit protection circuit (SCP) (Only available on BD9851EFV)

The SCP is a timer-latch type short circuit protection circuit.

If the output voltage of either channel drops below the set voltage, the Error Amp will be activated to increase the FB voltage and initiate charging the capacitor connected to the SCP pin with a 2 μA current. When the SCP pin voltage exceeds 1.5 V, the latch circuit will be activated to fix the output of both channels at OFF and, at the same time, the DTC pin at "L" level.

In order to rest the latch circuit, set the STB pin to "L" level once, and then to "H" level. Or, turn ON the power supply again.

Furthermore, if the short circuit protection circuit is not used, short-circuit the SCP pin to the GND pin.

8) Under Voltage Lock Out (UVLO) circuit

The UVLO is a protection circuit to prevent the IC from malfunctioning when the power supply turns ON or if an instantaneous power interruption occurs.

When the Vcc voltage falls below 3.8 V (or 3.7 V on the BD9851EFV), the output of both channels will be fixed at "OFF" and, at the same time, the DTC pin at "L" level. Hysteresis width of 0.1 V (or 0.11 V on the BD9851EFV) is provided for the detection voltage and release voltage of the UVLO in order to prevent malfunctions of the IC which may result from variations in the input voltage due to threshold online.

Furthermore, if the latch circuit is activated through the short circuit protection circuit, the circuit will be reset by this UVLO.

9) Thermal shutdown circuit (TSD)

The TSD is a protection circuit to prevent the destruction of the IC due to abnormal heat generation.

If the TSD detects an abnormal heat generation (175°C) on the chip, the output of both channels will be fixed at "OFF" and, at the same time, the DTC pin at "L" level. Hysteresis width (15°C) is provided for the superheat detection and release temperatures in order to prevent malfunctions of the IC which may result from variations in the input voltage due to threshold online.

Furthermore, if the latch circuit is activated through the short circuit protection circuit, the circuit will be reset by this TSD.

● Timing chart

- In startup/normal operation
(BD9850FVM)

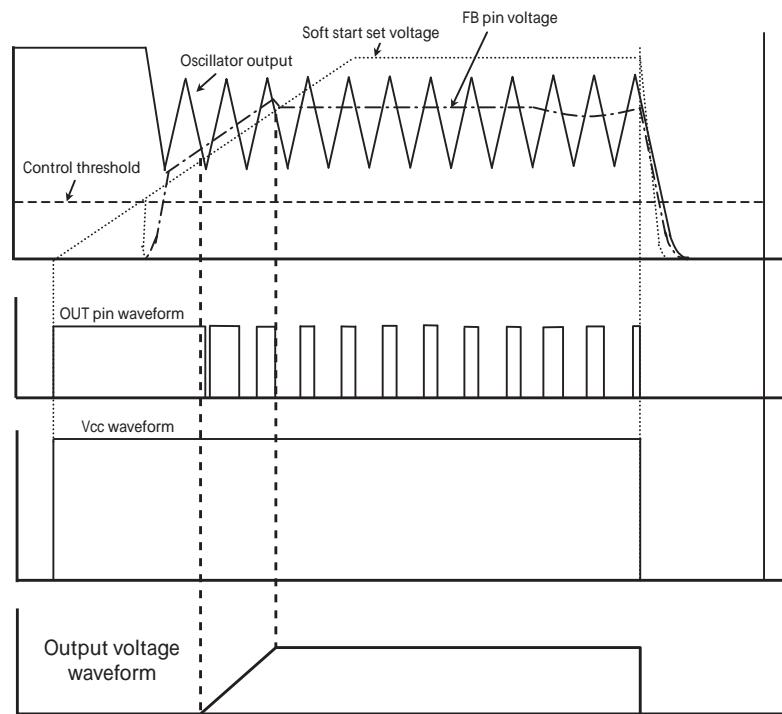


Fig.15 BD9850FVM Timing chart

(BD9851EFV)

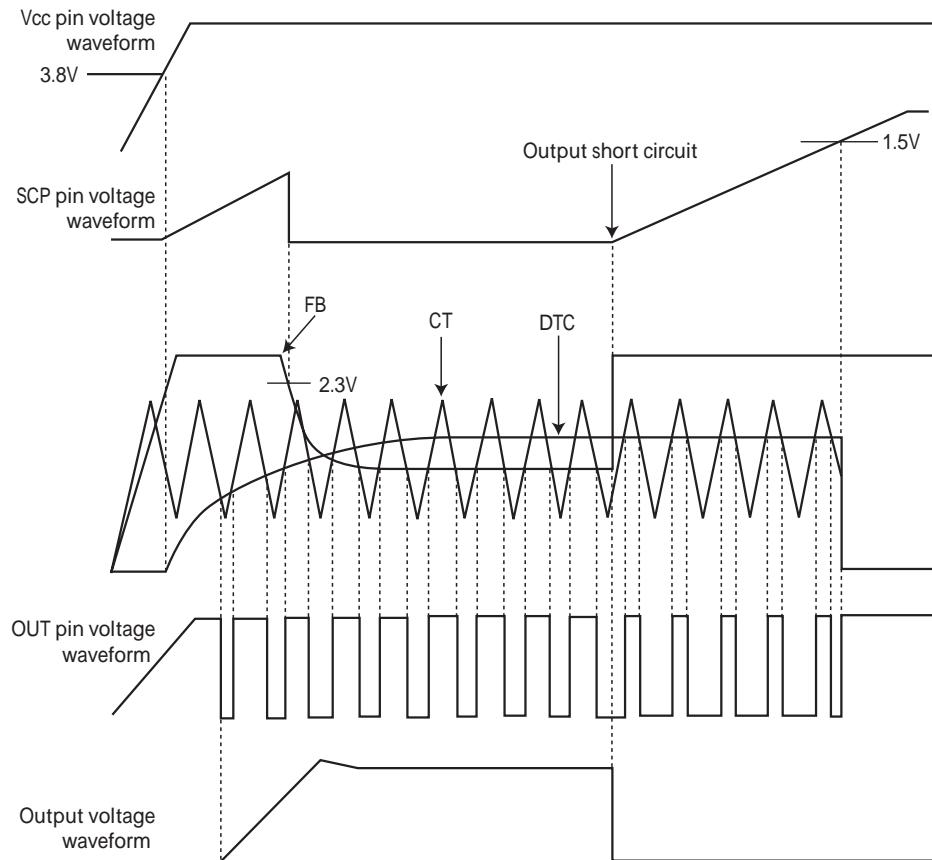
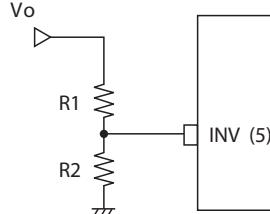


Fig.16 BD9851EFV Timing chart

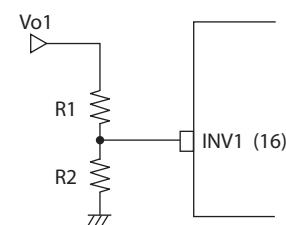
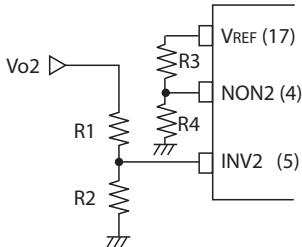
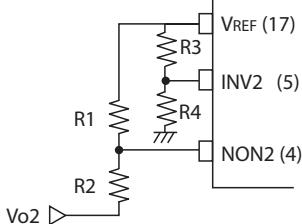
● Description of external components

- Setting of output voltage (BD9850FVM)

Setting of output voltage for the step-down application can be calculated by the formula below :

| Setting procedure | Application |
|---|--|
| $Vo = V_{thea} \times (R1 + R2) / R2 [V]$ $(V_{thea}: \text{Error Amp threshold voltage Typ. } 1.0 \text{ [V]})$ |  |

● Setting of output voltage (BD9851EFV)

| Setting procedure | Application |
|---|--|
| <ul style="list-style-type: none"> Step-down (CH1), Step-up (CH1) $Vo1 = V_{thea} \times (R1 + R2) / R2 [V]$ $(V_{thea}: \text{Error Amp threshold voltage Typ. } 1.0 \text{ [V]})$ |  |
| <ul style="list-style-type: none"> Step-down (CH2) $Vo2 = V_{NON2} \times (R1 + R2) / R2 [V]$ $V_{NON2} = 2.5 \times R4 / (R3 + R4) [V]$ However, set the NON2 pin voltage to 0.3 to 2.0 V. |  |
| <ul style="list-style-type: none"> Inverting (CH2) $Vo2 = 2.5 - \{ (2.5 - V_{INV2}) \times (R1 + R2) / R1 \} [V]$ $V_{INV2} = 2.5 \times R4 / (R3 + R4) [V]$ However, set the INV2 pin voltage to 0.3 to 2.0 V |  |

● Setting of oscillation frequency (BD9850FVM)

Connecting a resistor to the RT pin (pin 2) allows for the setting of oscillation frequency.

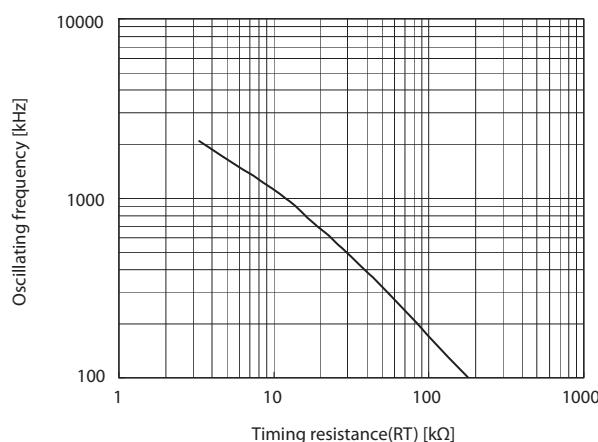


Fig.18 RT vs. Oscillation frequency

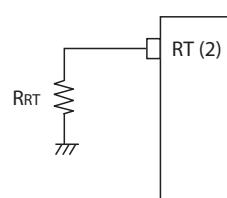


Fig.17 Setting procedure for BD9850FVM oscillation frequency

- Setting of oscillation frequency (BD9851EFV)

Connecting a resistor to the RT pin (pin 2) and a capacitor to the CT pin allows for the setting of oscillation frequency.

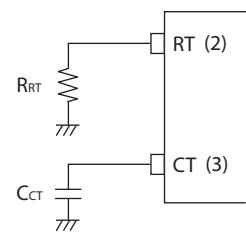


Fig. 19 Setting procedure for BD9851EFV oscillation frequency

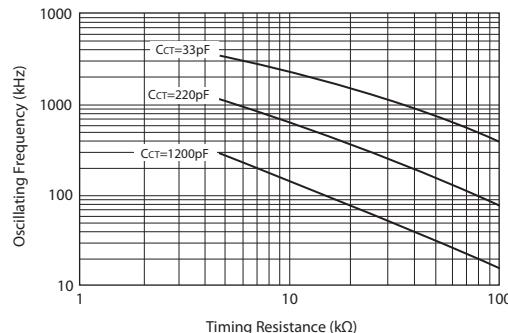


Fig. 20 RT vs. Oscillation frequency

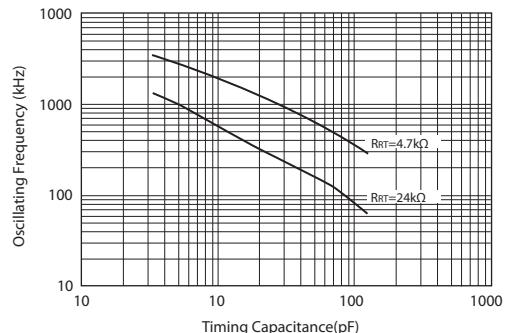


Fig. 20 CT vs. Oscillation frequency

- Setting of timer of short circuit protection circuit (BD9851EFV)

| Setting procedure | Application |
|--|-------------|
| $T_{SCP} = 7.45 \times 10^5 \times C_{SCP}$ T_{SCP} : Time from output short circuit to latch stop [sec] C_{SCP} : Capacitance of capacitor between the SCP and GND pins [F] | |

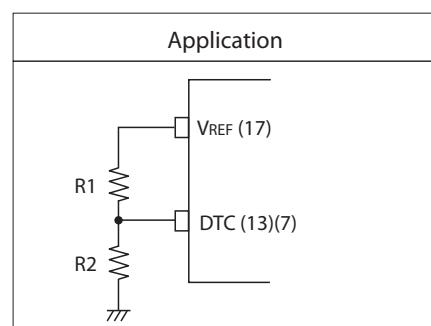
- Setting of maximum duty (BD9851EFV)

Setting procedure

$$DUTY(\text{max.}) = 100 \times (V_{DTC} - V_{th0}) / (V_{th100} - V_{th0})$$

$$V_{DTC} = 2.5 \times R2 / (R1 + R2)$$

$DUTY(\text{max.})$: Maximum duty [%]
 V_{DTC} : DTC pin voltage [V]
 V_{th0} : 0% duty threshold voltage [V]
 V_{th100} : 100% duty threshold voltage [V]



- Pin treatment of unused channels (BD9851EFV)

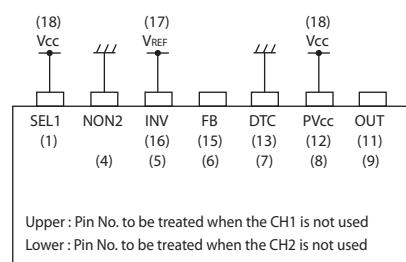
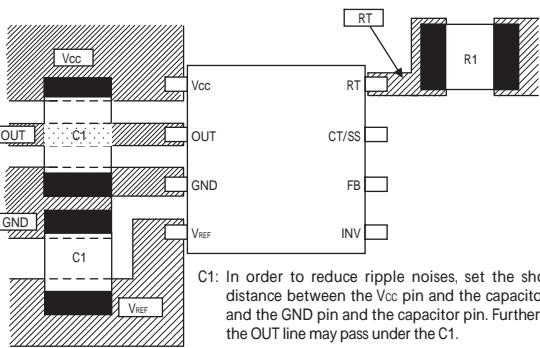
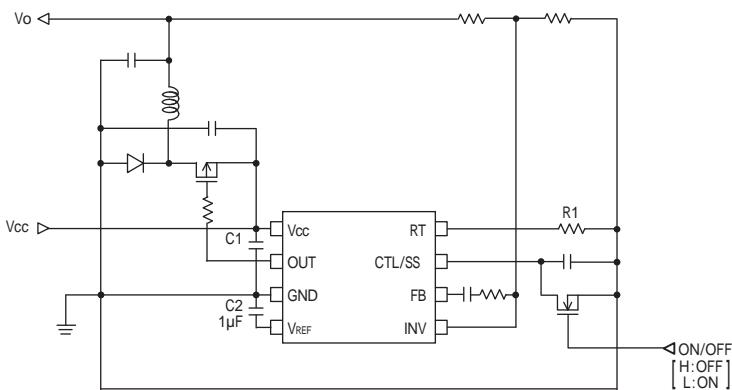


Fig. 22 Pin treatment procedure for unused channel on BD9851EFV

In order to use one channel, treat the pins of unused channel as shown above.

● Application circuit / Directions for pattern layout

(BD9850FVM)



C1: In order to reduce ripple noises, set the shortest distance between the Vcc pin and the capacitor pin, and the GND pin and the capacitor pin. Furthermore, the OUT line may pass under the C1.

C2: In order to reduce ripple noises, set the shortest pattern between the VREF pin and the capacitor pin, and the GND pin and the capacitor pin.

R1: In order to stabilize the switching frequency, set the smallest pattern area so that PCB parasitic capacitance for the RT pin will be minimized.

Fig.23 BD9850FVM Reference application

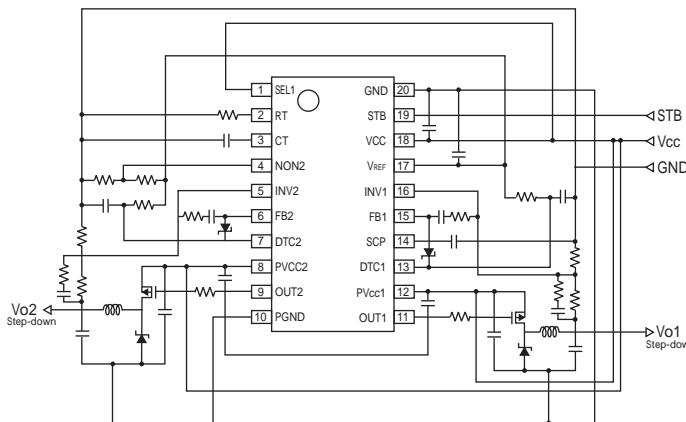


Fig.24 Step-down/Step-up application

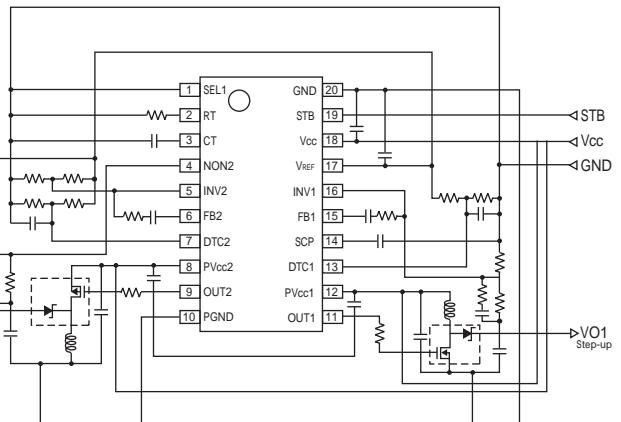


Fig.25 Step-up/Inverting application

● Equivalent circuit

(BD9850FVM)

| 2PIN(OUT) | 4PIN(VREF) | 5PIN(INV) |
|-----------|--------------|------------|
| | | |
| 6PIN(FB) | 7PIN(CTL/SS) | 8PIN(RT) |
| | | |

Fig.26 Equivalent circuit (BD9850FVM)

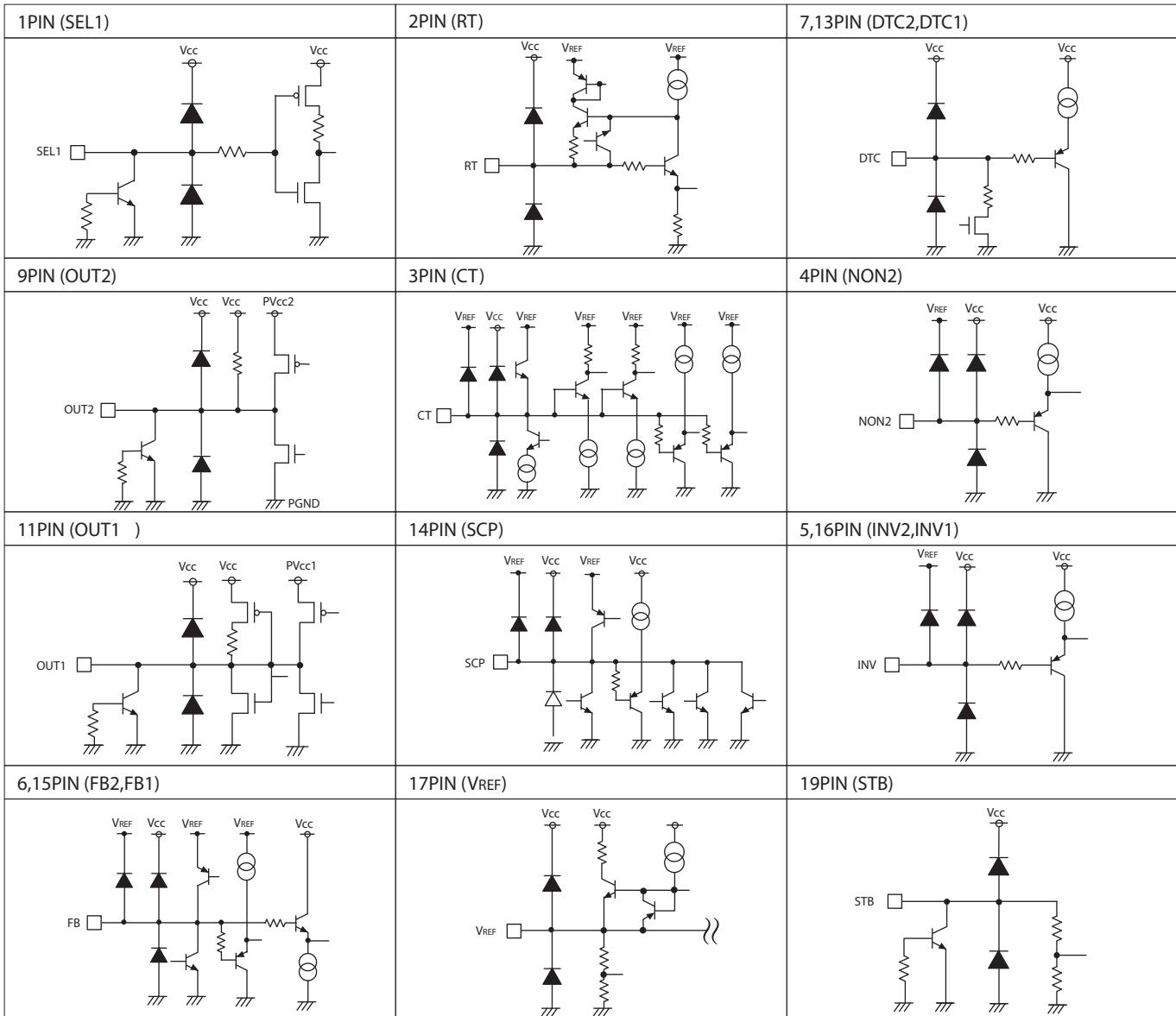


Fig.27 Equivalent circuit (BD9851EFV)

● Cautions on use

1) Absolute maximum ratings

An excess in the absolute maximum ratings, such as supply voltage, temperature range of operating conditions, etc., can break down the devices, thus making impossible to identify breaking mode, such as a short circuit or an open circuit. If any over rated values will expect to exceed the absolute maximum ratings, consider adding circuit protection devices, such as fuses.

2) GND potential

Ground-GND potential should maintain at the minimum ground voltage level. Furthermore, no terminals should be lower than the GND potential voltage including an electric transients.

3) Thermal design

Use a thermal design that allows for a sufficient margin in light of the power dissipation (Pd) in actual operating conditions.

4) Inter-pin shorts and mounting errors

Use caution when positioning the IC for mounting on printed circuit boards. The IC may be damaged if there is any connection error or if positive and ground power supply terminals are reversed. The IC may also be damaged if pins are shorted together or are shorted to other circuit's power lines.

5) Operation in strong electromagnetic field

Use caution when using the IC in the presence of a strong electromagnetic field as doing so may cause the IC to malfunction.

6) Thermal shutdown circuit (TSD circuit)

The IC incorporates a built-in thermal shutdown circuit (TSD circuit). The thermal shutdown circuit (TSD circuit) is designed only to shut the IC off to prevent runaway thermal operation. It is not designed to protect the IC or guarantee its operation. Do not continue to use the IC after operating this circuit or use the IC in an environment where the operation of this circuit is assumed.

7) Testing on application boards

When testing the IC on an application board, connecting a capacitor to a pin with low impedance subjects the IC to stress. Always discharge capacitors after each process or step. Always turn the IC's power supply off before connecting it to, or removing it from a jig or fixture, during the inspection process. Ground the IC during assembly steps as an antistatic measure. Use similar precaution when transporting and storing the IC.

8) IC pin input

This monolithic IC contains P+ isolation and P substrate layers between adjacent elements to keep them isolated. Pin junctions are formed at the intersection of these P layers with the N layers of other elements, creating a parasitic diode or transistor. For example, the relation between each potential is as follows:

When GND > Pin A and GND > Pin B, the Pin junction operates as a parasitic diode.

When Pin B > GND > Pin A, the P+N junction operates as a parasitic transistor.

Parasitic diodes can occur inevitably in the structure of the IC. The operation of parasitic diodes can result in mutual interference among circuits, operational faults, or physical damage. Accordingly, methods by which parasitic diodes operate, such as applying a voltage that is lower than the GND (P substrate) voltage to an input pin, should not be used.

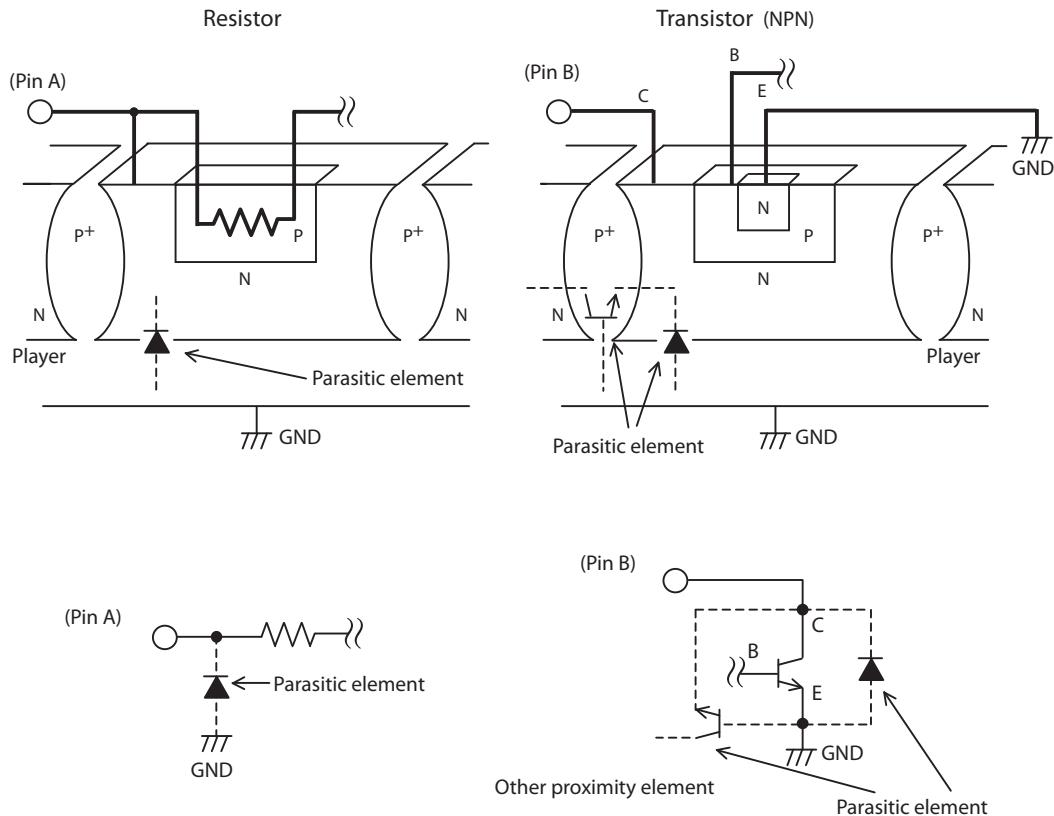


Fig. 28 Typical simple construction of monolithic IC

9) Common impedance

The power supply and ground lines must be as short and thick as possible to reduce line impedance. Fluctuating voltage on the power ground line may damage the device.

10) On the application shown below, Vcc is short-circuited to the Ground with external diode charged, internal circuits may be damaged. recommended to insert a backflow prevention diode in series with the Vcc or a bypass diode between each pin and Vcc.

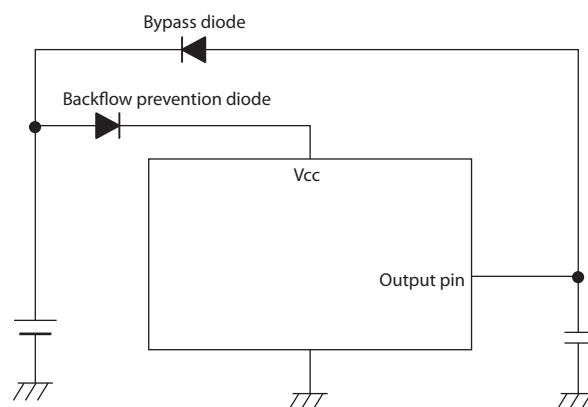


Fig. 29

11) Although ROHM is confident that the example application circuit reflects the best possible recommendations, be sure to verify circuit characteristics for your particular application. Modification of constants for other externally connected circuits may cause variations in both static and transient characteristics for external components as well as this Rohm IC. Allow for sufficient margins when determining circuit constants.

Oscillation frequency setting resistor

12) For the oscillation frequency setting resistor to be inserted between the RT pin and the GND pin, mount this resistor close to the RT pin and provide the shortest pattern routing.

● Thermal derating characteristics

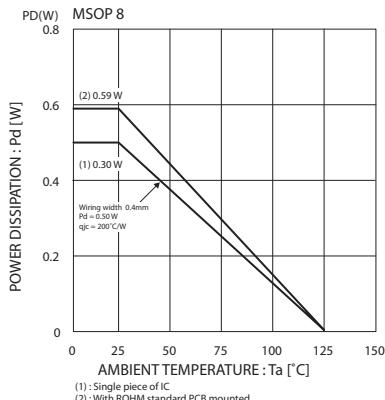


Fig.30

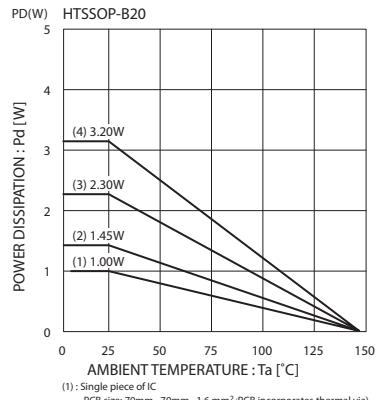
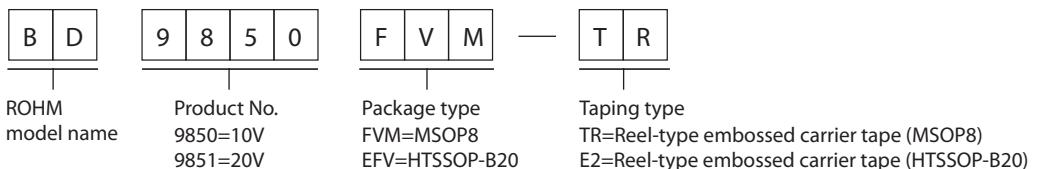
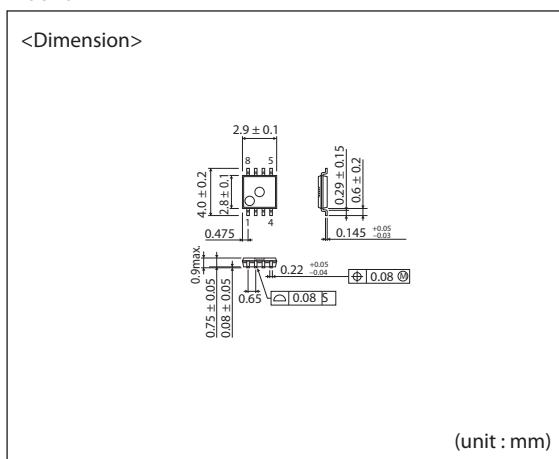


Fig.31

● Selection of order type

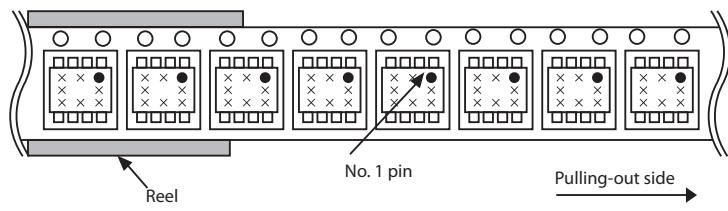


MSOP8

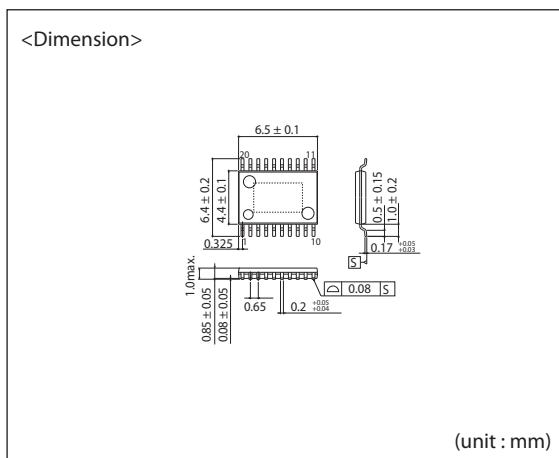


<Package specifications>

| | |
|---------------------|--|
| Package style | Embossed carrier tape |
| Quantity | 3000 pieces/reel |
| Packaging direction | TR (When holding a reel in left hand and pulling out the tape with right hand, No. 1 pin appears in the upper right of the reel.) |

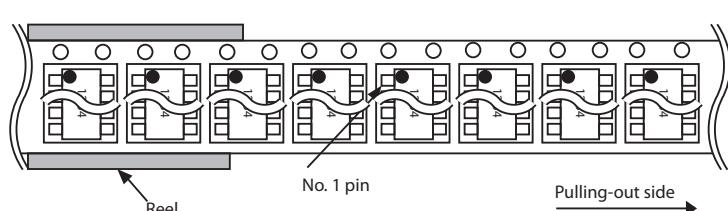


HTSSOP-B20



<Package specifications>

| | |
|---------------------|---|
| Package style | Embossed carrier tape (Moisture-proof specification) |
| Quantity | 2500 pieces/reel |
| Packaging direction | E2 (When holding a reel in left hand and pulling out the tape with right hand, No. 1 pin appears in the upper left of the reel.) |



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